

What is claimed is:

1           1. A laminate support used in the process of wire  
2 bonding a circuit device, comprising a closed woven mesh  
3 having strands whose separation distance is equal to or less  
4 than the diameter of said wire of said circuit device.

1           2. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 1, wherein  
3 said separation distance is no greater than 0.7 mils.

1           3. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 1, wherein  
3 said separation distance is between 0.2 and 0.7 mils.

1           4. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 1, wherein  
3 said laminate support comprises fiberglass.

1           5. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 1, wherein  
3 said laminate support is between approximately 2.5 and 4  
4 mils thick.

1           6. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 1, wherein  
3 said circuit device is a pad of large scale integrated  
4 design.

1           7. A laminate support used in the process of wire  
2 bonding a circuit device, comprising a closed woven mesh  
3 having warp and weave strands, whose separation distance is  
4 equal to or less than the thickness of said wire of said  
5 circuit device, as measured lengthwise through said closed  
6 woven mesh.

1           8. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 7, wherein  
3 said separation distance is equal to or less than 0.7 mils.

1           9. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 7, wherein  
3 said separation distance is between 0.2 and 0.7 mils.

1           10. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 7, wherein  
3 said laminate support comprises fiberglass.

1           11. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 7, wherein  
3 said laminate support is between approximately 2.5 and 4  
4 mils thick.

1           12. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 7, wherein  
3 said circuit device comprises a pad of large scale  
4 integrated design.

1           13. A laminate support used in the process of wire  
2 bonding a circuit device, comprising a closed woven mesh  
3 having warp and weave strands, whose separation distance is  
4 no greater than the diameter of said wire of said circuit  
5 device as measured lengthwise through said closed woven  
6 mesh, and wherein said separation distance is approximately  
7 equal to or less than 0.7 mils.

1           14. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 13,  
3 wherein said separation distance is between 0.2 and 0.7  
4 mils.

1           15. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 13,  
3 wherein said laminate support comprises fiberglass.

1           16. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 13,  
3 wherein said laminate support is between approximately 2.5  
4 and 4 mils thick.

1           17. The laminate support used in the process of wire  
2 bonding a circuit device in accordance with claim 13,  
3 wherein said circuit device comprises a pad of large scale  
4 integrated design.

1           18. A method for supporting a circuit device during  
2 wire bonding, comprising the steps of:

3           a) applying a capillary tool to wire that is to  
4 be bonded to a circuit device; and

5           b) supporting said circuit device upon a closed  
6 woven mesh whose separation distance between woven strands  
7 is less than or equal to a diameter of said wire.

1           19. The method of claim 18, wherein said separation  
2 distance is approximately equal to or less than 0.7 mils.

1           20. The method of claim 18, wherein said separation  
2 distance is between approximately 0.2 and 0.7 mils.